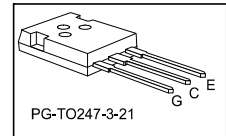
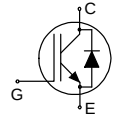


Low Loss DuoPack : IGBT in TrenchStop® and Fieldstop technology with soft, fast recovery anti-parallel diode

- TrenchStop® and Fieldstop technology for 1000 V applications offers:
 - low $V_{CE(sat)}$
 - very tight parameter distribution
 - high ruggedness, temperature stable behavior
 - positive temperature coefficient in $V_{CE(sat)}$
- Designed for:
 - frequency Converters
 - uninterrupted Power Supply
- Low EMI
- Low gate charge
- Very soft, fast recovery anti-parallel diode
- Qualified according to JEDEC for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models:
<http://www.infineon.com/igbt/>



Type	V_{CE}	I_C	$V_{CE(sat)}$ $T_j=25^\circ\text{C}$	T_{jmax}	Marking	Package
IKW30N100T	1000V	30A	1.55V	175°C	K30T100	PG-TO247-3-21

Maximum ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1000	V
DC collector current, limited by T_{jmax} $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_C	60.0 30.0	A
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	90.0	A
Turn off safe operating area $V_{CE} = 1000\text{V}$, $T_j = 175^\circ\text{C}$	-	90.0	A
Diode forward current, limited by T_{jmax} $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_F	60.0 30.0	A
Diode pulsed current, t_p limited by T_{jmax}	I_{Fpuls}	90.0	A
Gate-emitter voltage Transient Gate-emitter voltage ($t_p = 5\mu\text{s}$, $D < 0.010$)	V_{GE}	± 20 ± 25	V
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	412.0	W
Operating junction temperature	T_j	-55...+175	°C
Storage temperature	T_{stg}	-55...+175	°C
Soldering temperature, wavesoldering 1.6 mm (0.063 in.) from case for 10s	PG-TO247-3-21	260	°C
Mounting torque, M3 screw Maximum of mounting processes: 3	M	0.6	Nm

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction - case	R_{thJC}		0.36	K/W
Diode thermal resistance, junction - case	R_{thJCD}		0.80	K/W
Thermal resistance junction - ambient	R_{thJA}	PG-TO247-3-21	40	K/W

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0V, I_C = 0.50mA$	1000	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15.0V, I_C = 30.0A$ $T_j = 25^{\circ}C$ $T_j = 150^{\circ}C$ $T_j = 175^{\circ}C$	- - -	1.55 1.70 1.80	1.90 - -	V
Diode forward voltage	V_F	$V_{GE} = 0V, I_F = 30.0A$ $T_j = 25^{\circ}C$ $T_j = 150^{\circ}C$ $T_j = 175^{\circ}C$	- - -	1.65 1.70 1.65	2.20 -	V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 0.80mA, V_{CE} = V_{GE}$	5.1	5.8	6.4	V
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1000V, V_{GE} = 0V$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	- -	- -	50.0 2500.0	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = 20V$	-	-	600	nA
Transconductance	g_{fs}	$V_{CE} = 20V, I_C = 30.0A$	-	28.0	-	S
Integrated gate resistor	R_{Gint}			none		Ω

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristic						
Input capacitance	C_{iss}	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$	-	3575	-	pF
Output capacitance	C_{oss}		-	98	-	
Reverse transfer capacitance	C_{rss}		-	76	-	
Gate charge	Q_{Gate}	$V_{CC} = 800V, I_c = 30.0A, V_{GE} = 15V$	-	217.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E	PG-TO247-3-21	-	13.0	-	nH

Switching Characteristic, Inductive Load, at $T_j = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j = 25^{\circ}\text{C}$, $V_{CC} = 600\text{V}$, $I_C = 30.0\text{A}$, $V_{GE} = 0.0/15.0\text{V}$, $R_G = 16.0\Omega$, $L_{\sigma} = 105\text{nH}$, $C_{\sigma} = 50\text{pF}$ L_{σ} , C_{σ} from Fig. E Energy losses include “tail” and diode reverse recovery.	-	33	-	ns
Rise time	t_r		-	21	-	ns
Turn-off delay time	$t_{d(off)}$		-	535	-	ns
Fall time	t_f		-	34	-	ns
Turn-on energy	E_{on}		-	2.20	-	mJ
Turn-off energy	E_{off}		-	1.60	-	mJ
Total switching energy	E_{ts}		-	3.80	-	mJ

Anti-Parallel Diode Characteristic, at $T_j = 25^\circ\text{C}$

Diode reverse recovery time	t_{rr}	$T_j = 25^\circ\text{C}$, $V_R = 600\text{V}$, $I_F = 30.0\text{A}$, $di_F/dt = 1000\text{A}/\mu\text{s}$	-	230	-	ns
Diode reverse recovery charge	Q_{rr}		-	2.10	-	μC
Diode peak reverse recovery current	I_{rrm}		-	21.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	560	-	A/ μs

Switching Characteristic, Inductive Load, at $T_j = 175^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j = 175^{\circ}\text{C}$, $V_{CC} = 600\text{V}$, $I_C = 30.0\text{A}$, $V_{GE} = 0.0/15.0\text{V}$, $R_G = 16.0\Omega$, $L_{\sigma} = 105\text{nH}$, $C_{\sigma} = 50\text{pF}$ L_{σ} , C_{σ} from Fig. E Energy losses include “tail” and diode reverse recovery.	-	33	-	ns
Rise time	t_r		-	30	-	ns
Turn-off delay time	$t_{d(off)}$		-	610	-	ns
Fall time	t_f		-	60	-	ns
Turn-on energy	E_{on}		-	3.20	-	mJ
Turn-off energy	E_{off}		-	2.40	-	mJ
Total switching energy	E_{ts}		-	5.60	-	mJ

Anti-Parallel Diode Characteristic, at $T_j = 175^\circ\text{C}$

Diode reverse recovery time	t_{rr}	$T_j = 175^\circ\text{C}$, $V_R = 600\text{V}$, $I_F = 30.0\text{A}$, $di_F/dt = 1000\text{A}/\mu\text{s}$	-	340	-	ns
Diode reverse recovery charge	Q_{rr}		-	4.70	-	μC
Diode peak reverse recovery current	I_{rrm}		-	28.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	290	-	A/ μs

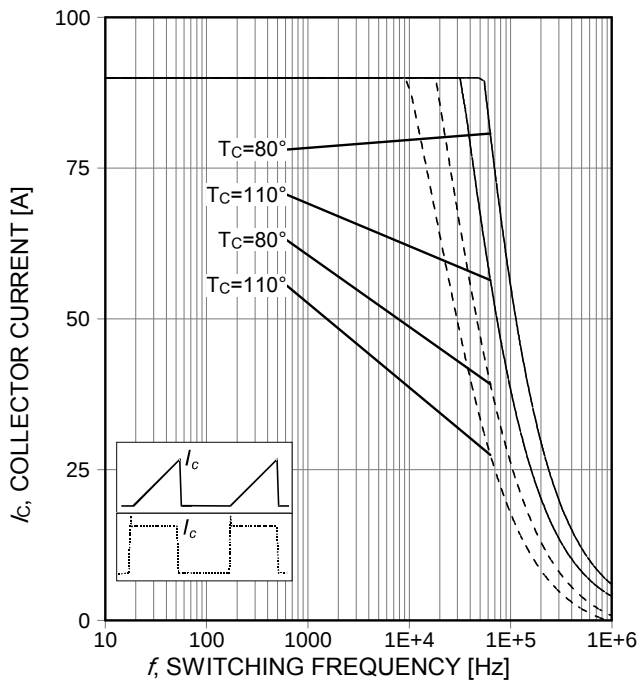


Figure 1. Collector current as a function of switching frequency
($T_J \leq 175^\circ\text{C}$, $D=0.5$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=16\Omega$)

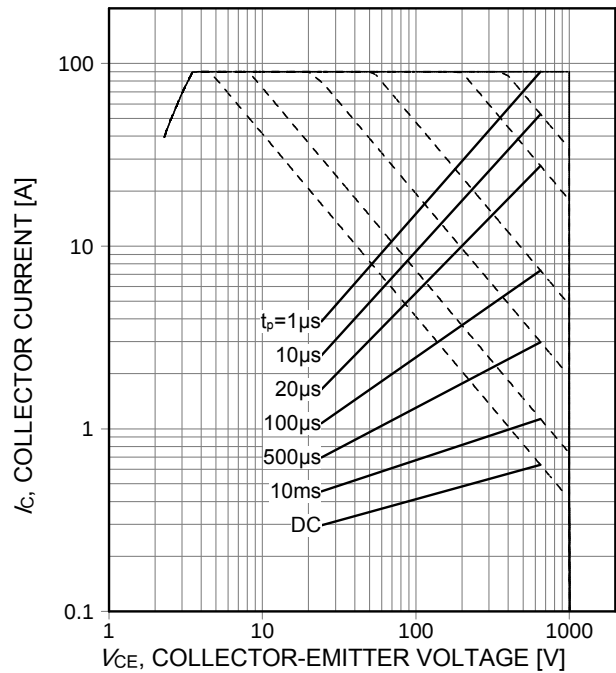


Figure 2. Forward bias safe operating area
($D=0$, $T_C=25^\circ\text{C}$, $T_J \leq 175^\circ\text{C}$; $V_{GE}=15\text{V}$)

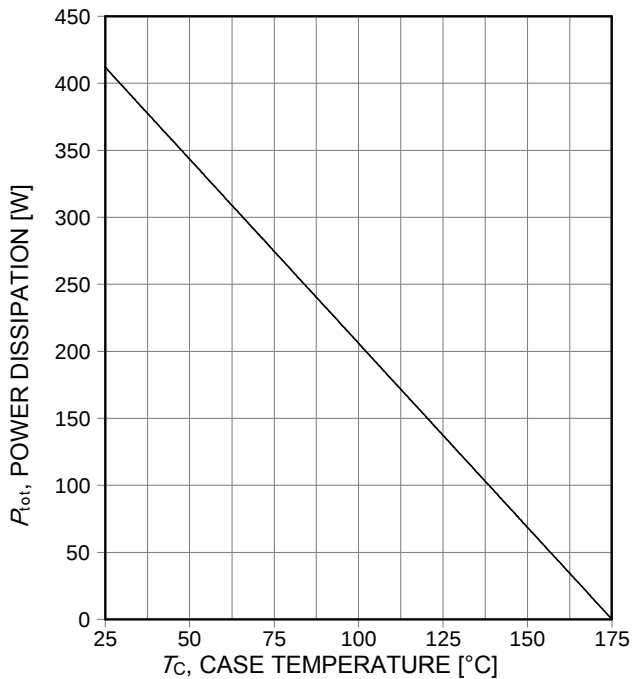


Figure 3. Power dissipation as a function of case temperature
($T_J \leq 175^\circ\text{C}$)

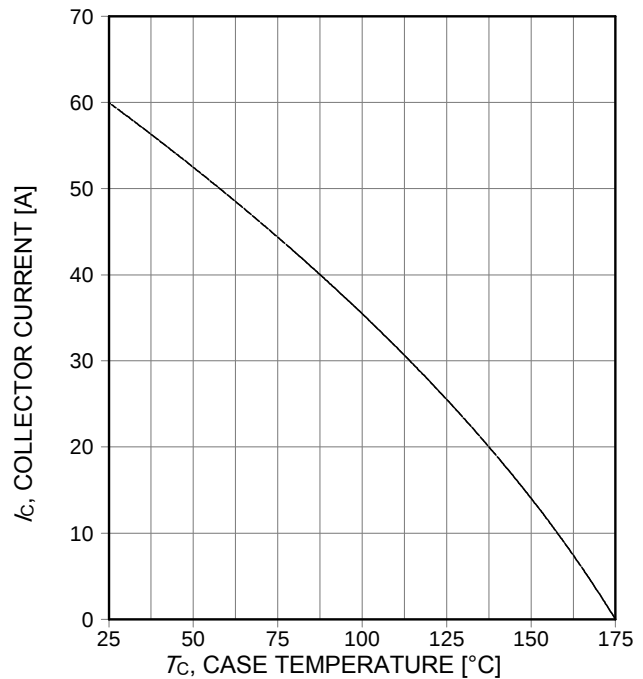


Figure 4. Collector current as a function of case temperature
($V_{GE} \geq 15\text{V}$, $T_J \leq 175^\circ\text{C}$)

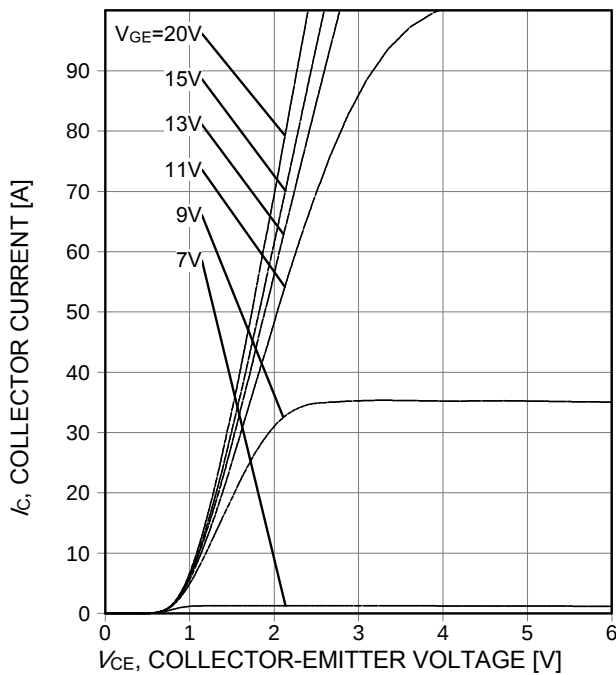


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

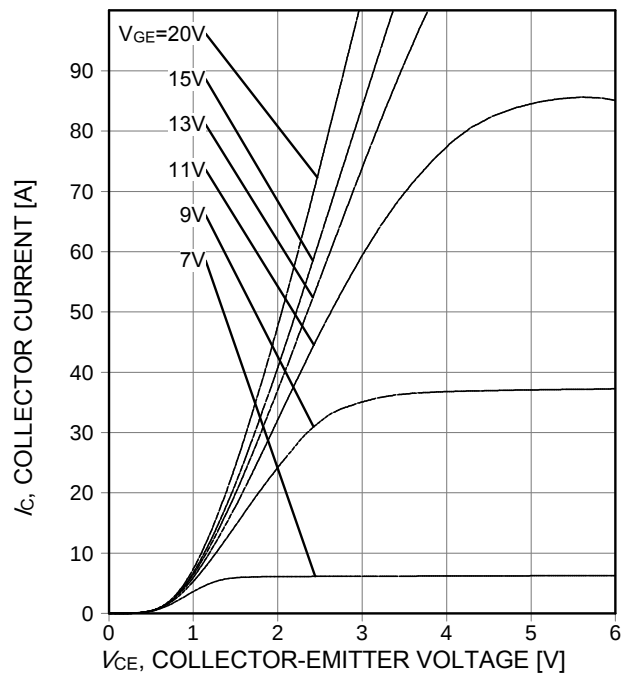


Figure 6. Typical output characteristic
($T_j = 175^\circ\text{C}$)

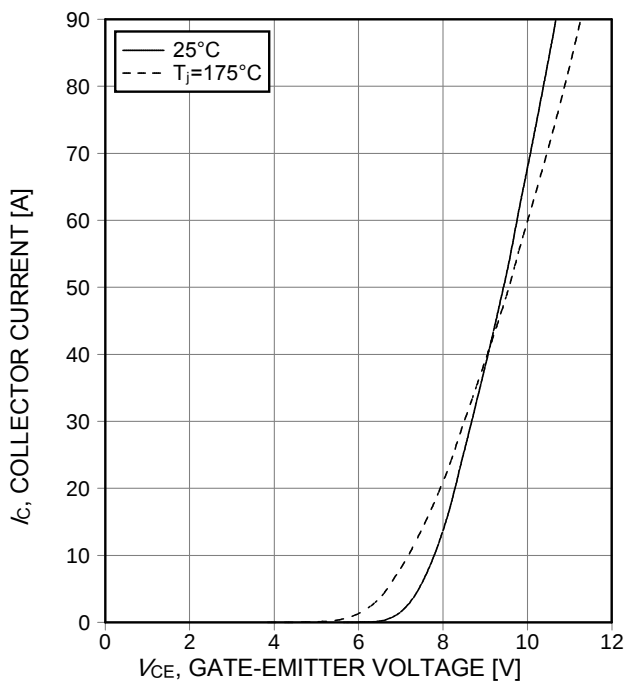


Figure 7. Typical transfer characteristic
($V_{CE} = 20\text{V}$)

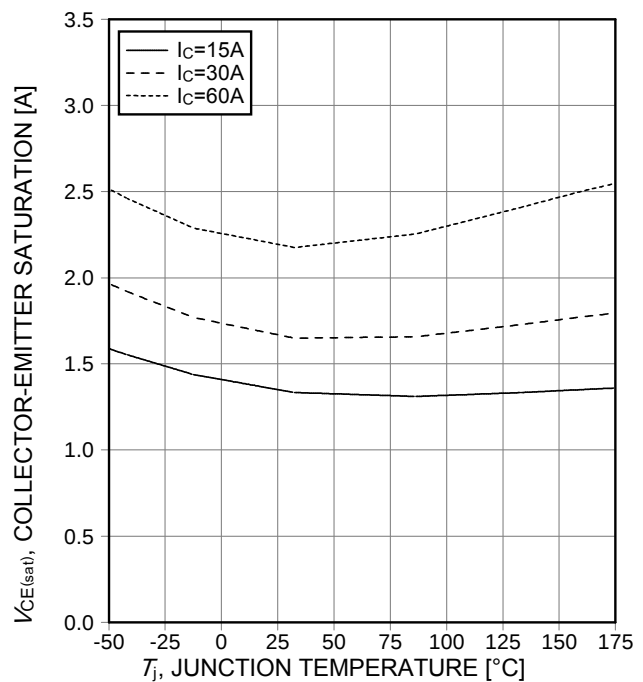


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

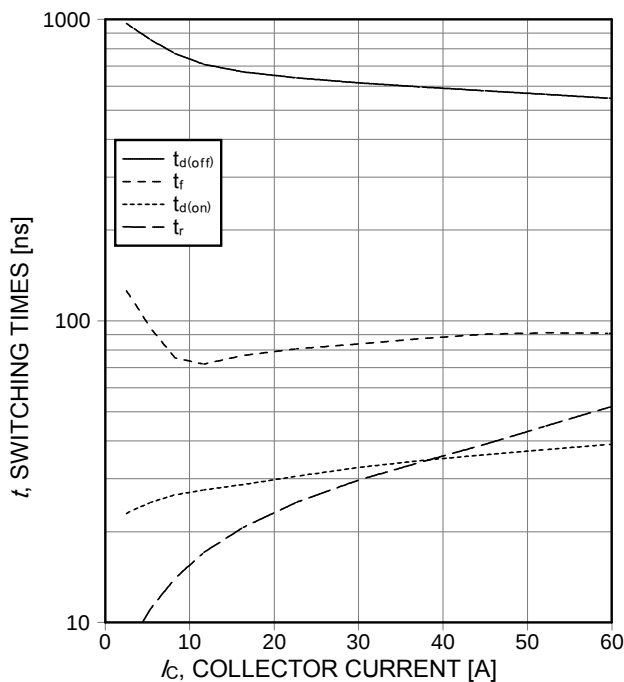


Figure 9. Typical switching times as a function of collector current
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=16\Omega$, Dynamic test circuit in Figure E)

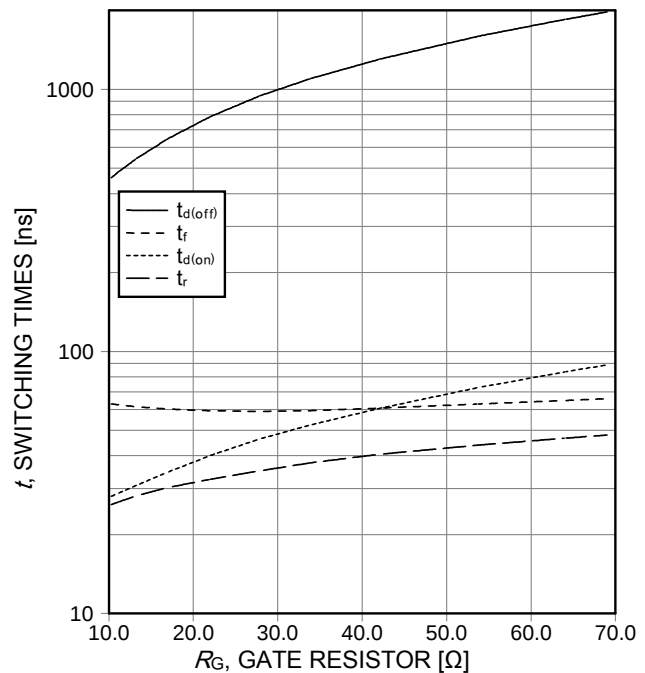


Figure 10. Typical switching times as a function of gate resistor
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=30\text{A}$, Dynamic test circuit in Figure E)

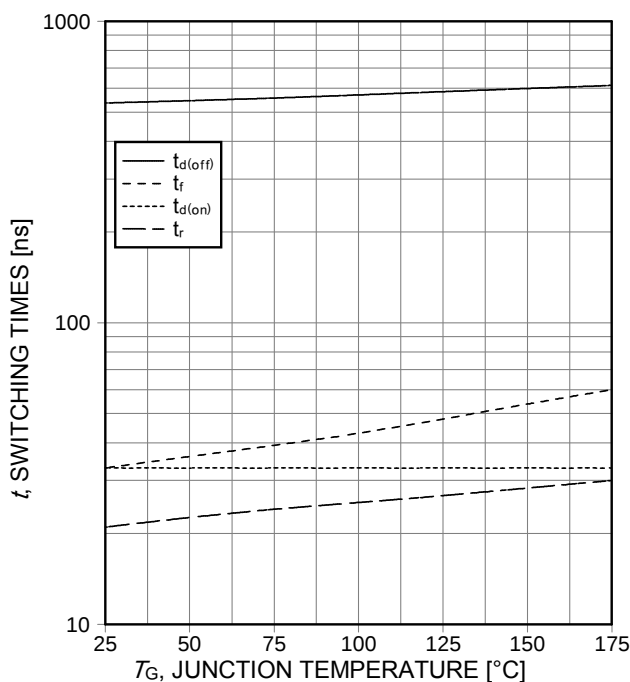


Figure 11. Typical switching times as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=30\text{A}$, $R_G=16\Omega$, Dynamic test circuit in Figure E)

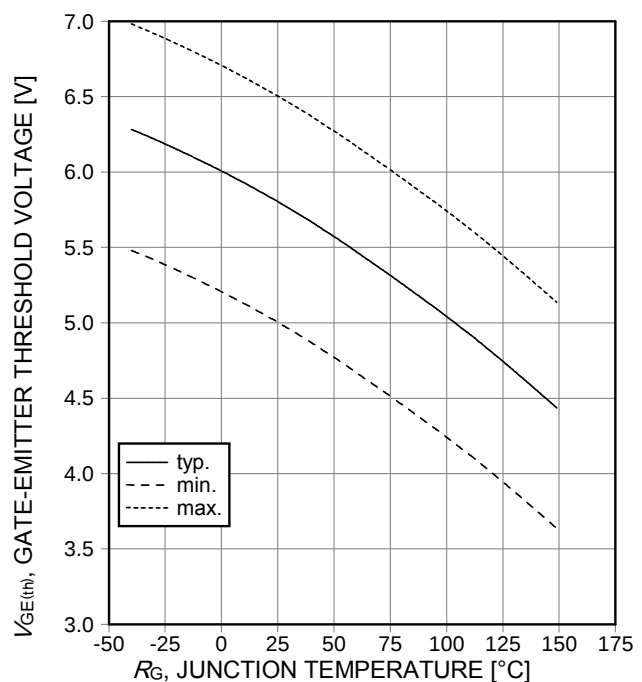


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
($I_C=0.7\text{mA}$)

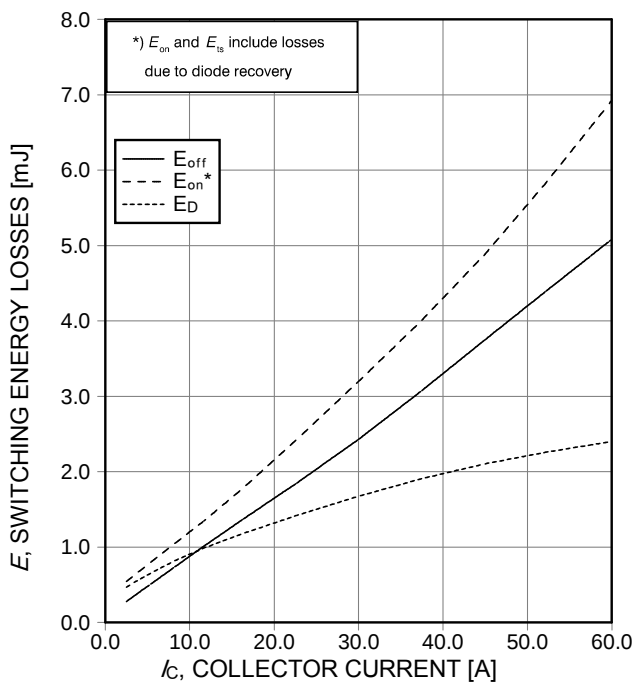


Figure 13. Typical switching energy losses as a function of collector current
(inductive load, $T_j=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=16\Omega$, Dynamic test circuit in Figure E)

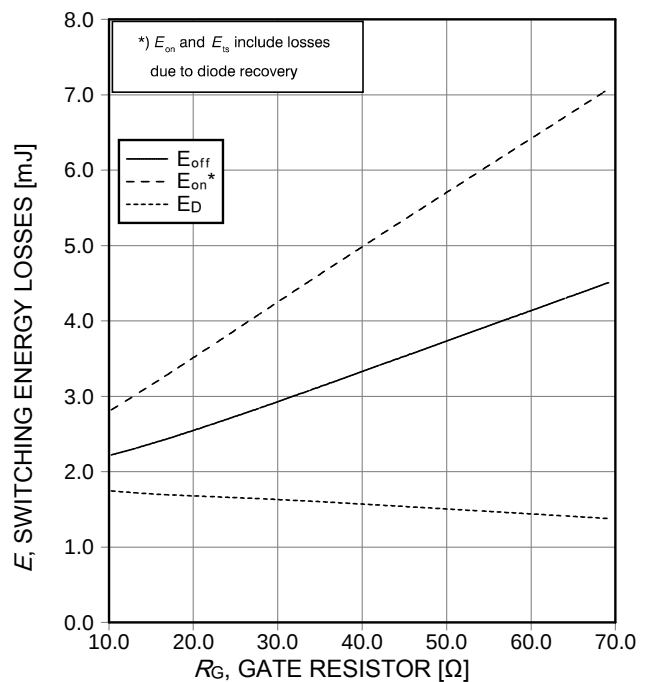


Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, $T_j=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=16\Omega$, Dynamic test circuit in Figure E)

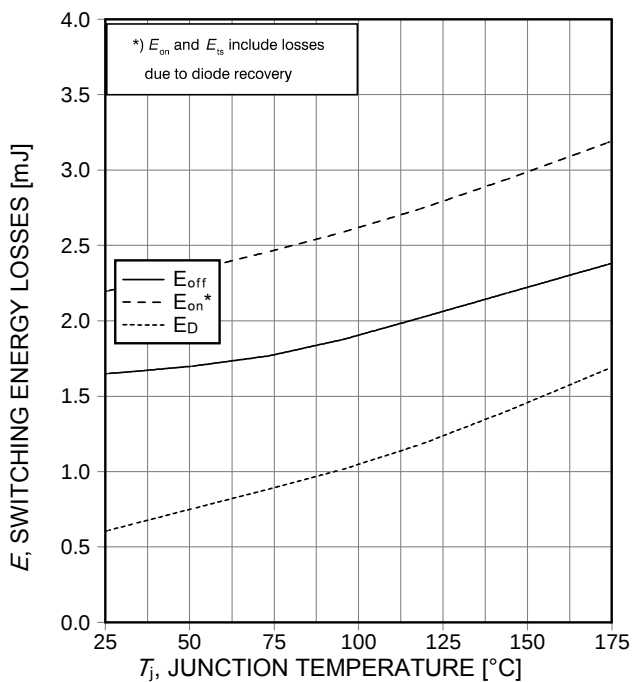


Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=30\text{A}$, $R_G=16\Omega$, Dynamic test circuit in Figure E)

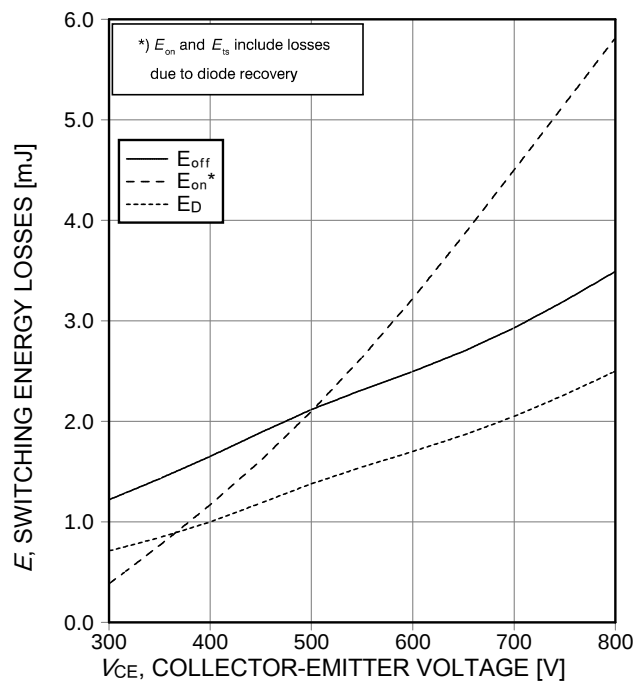


Figure 16. Typical switching energy losses as a function of collector emitter voltage
(inductive load, $T_j=175^\circ\text{C}$, $V_{GE}=15/0\text{V}$, $I_C=30\text{A}$, $R_G=16\Omega$, Dynamic test circuit in Figure E)

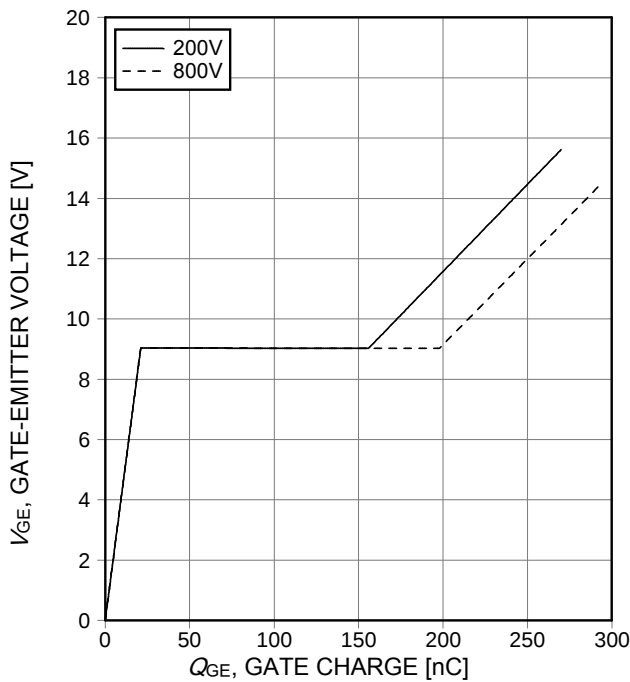


Figure 17. Typical gate charge
($I_C=30A$)

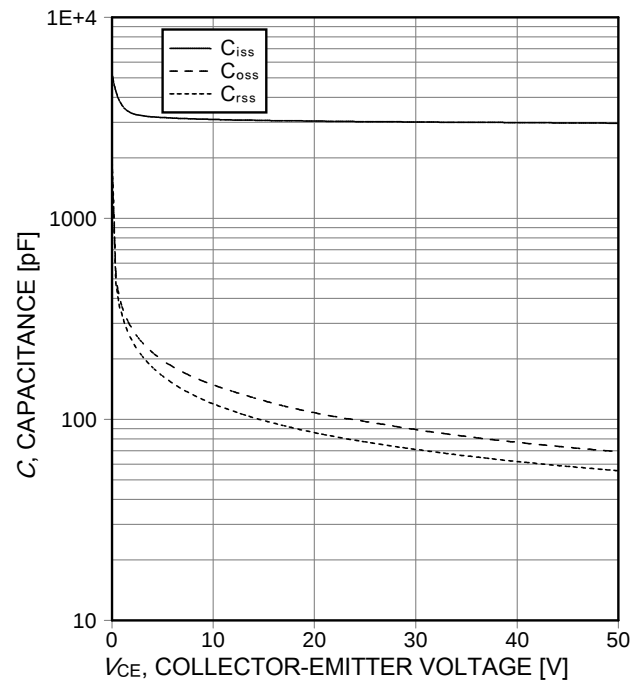


Figure 18. Typical capacitance as a function of
collector-emitter voltage
($V_{GE}=0V$, $f=1MHz$)

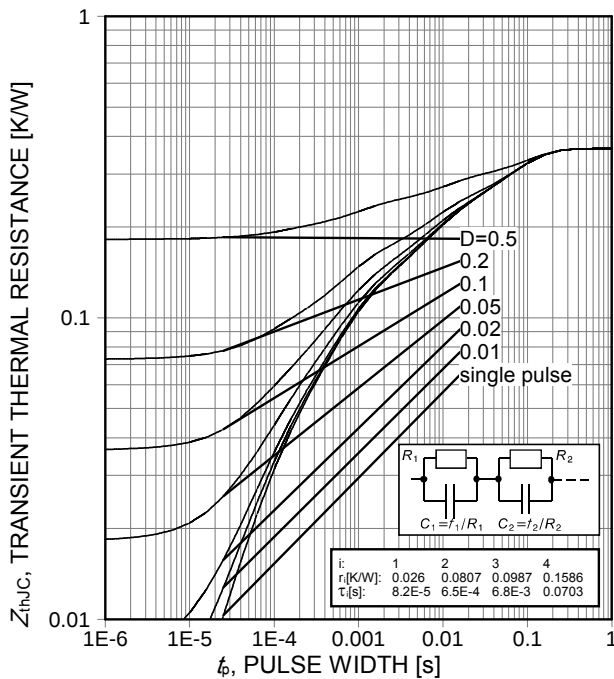


Figure 19. IGBT transient thermal resistance
($D=t_p/T$)

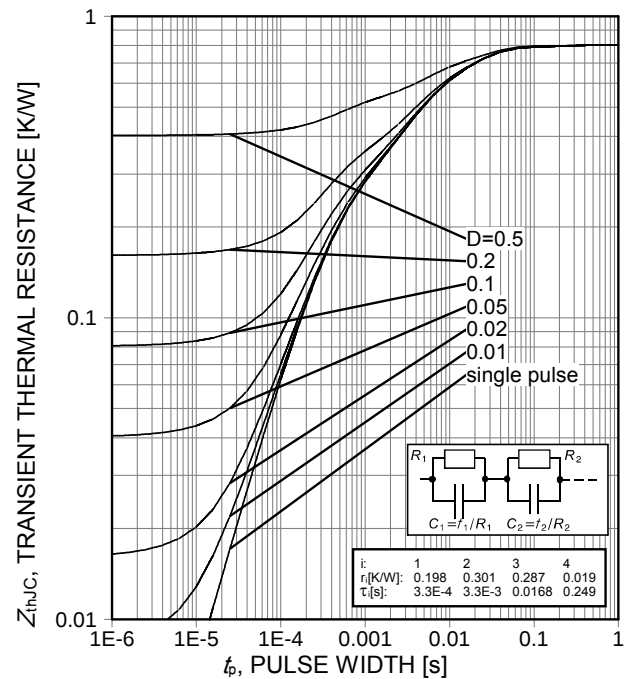


Figure 20. Diode transient thermal impedance as a
function of pulse width
($D=t_p/T$)

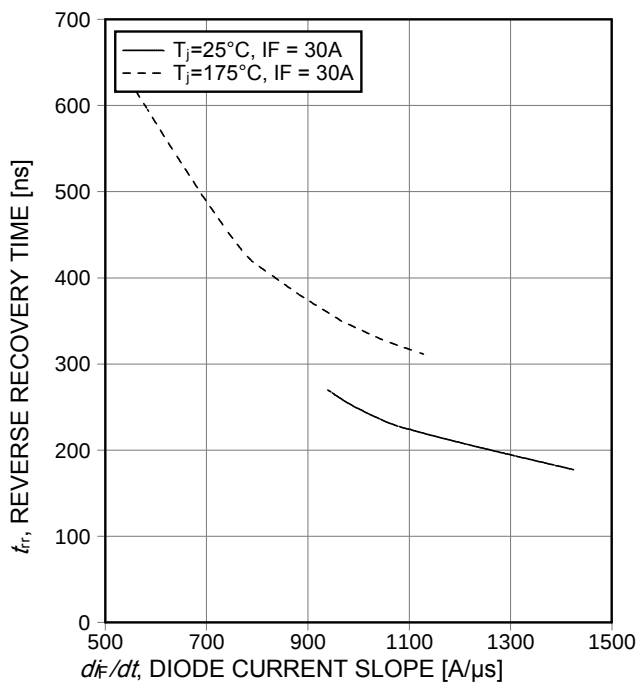


Figure 21. Typical reverse recovery time as a function of diode current slope
($V_R=600V$)

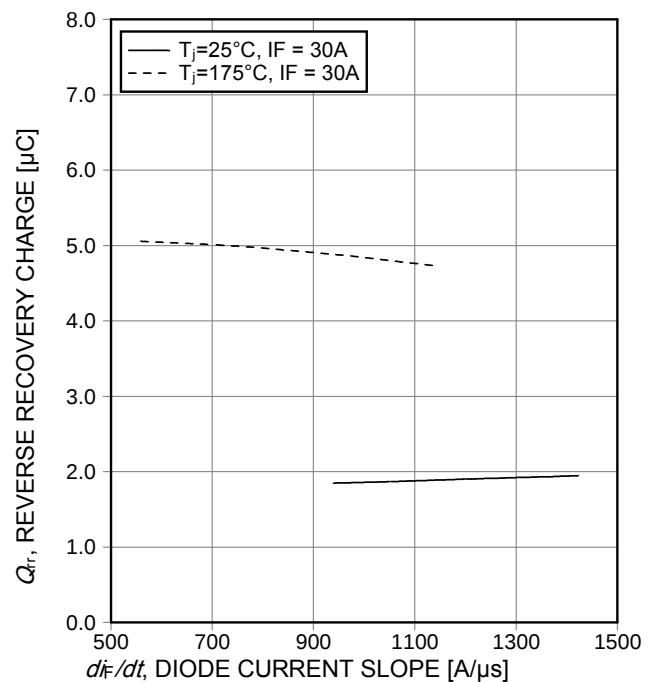


Figure 22. Typical reverse recovery charge as a function of diode current slope
($V_R=600V$)

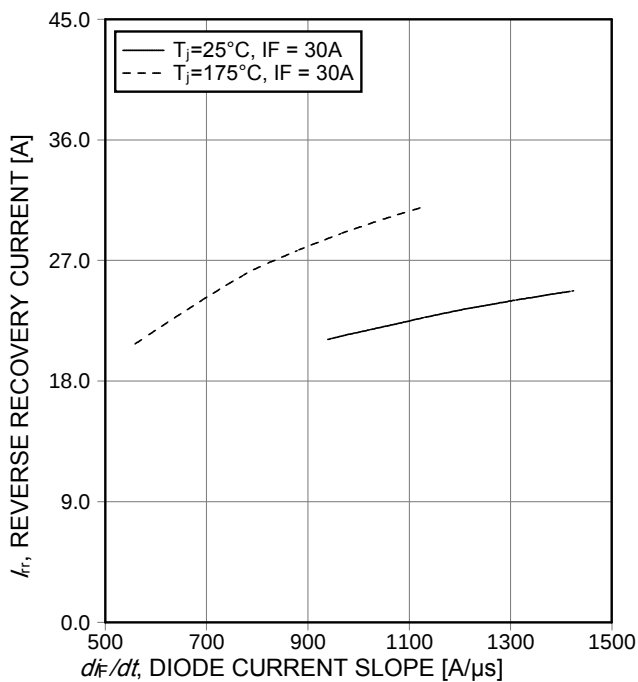


Figure 23. Typical reverse recovery current as a function of diode current slope
($V_R=600V$)

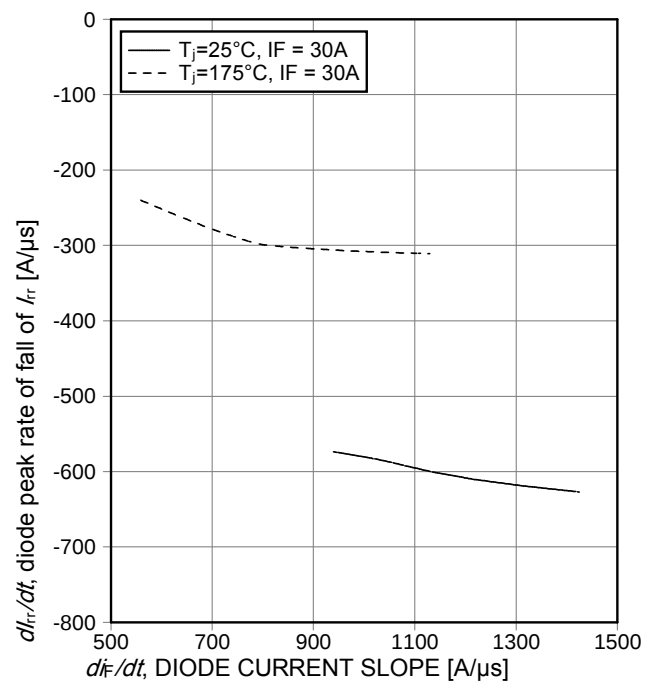


Figure 24. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope
($V_R=600V$)

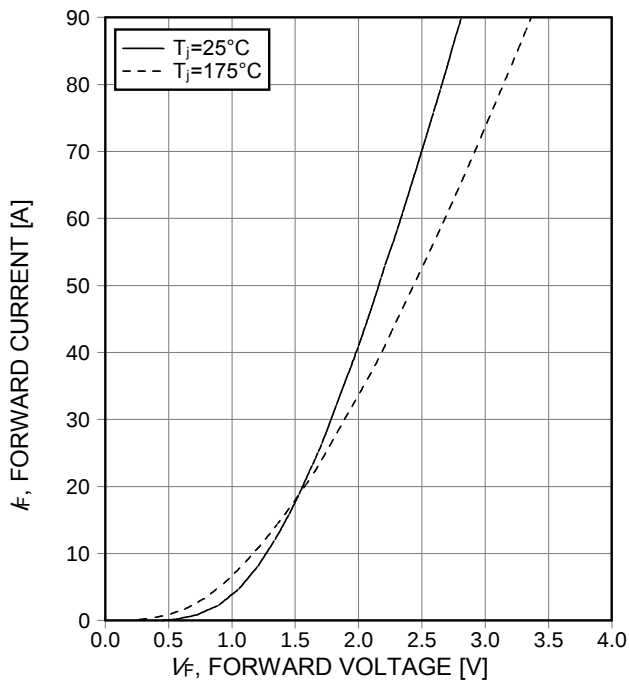


Figure 25. Typical diode forward current as a function of forward voltage

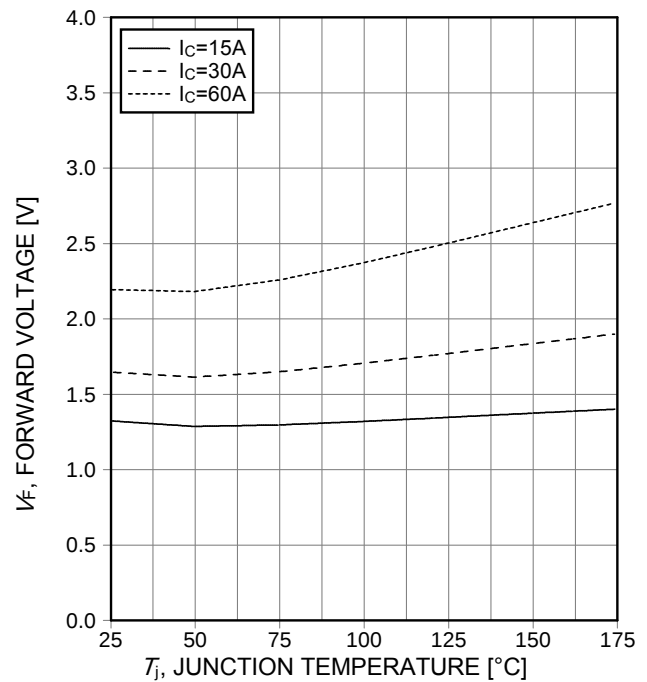
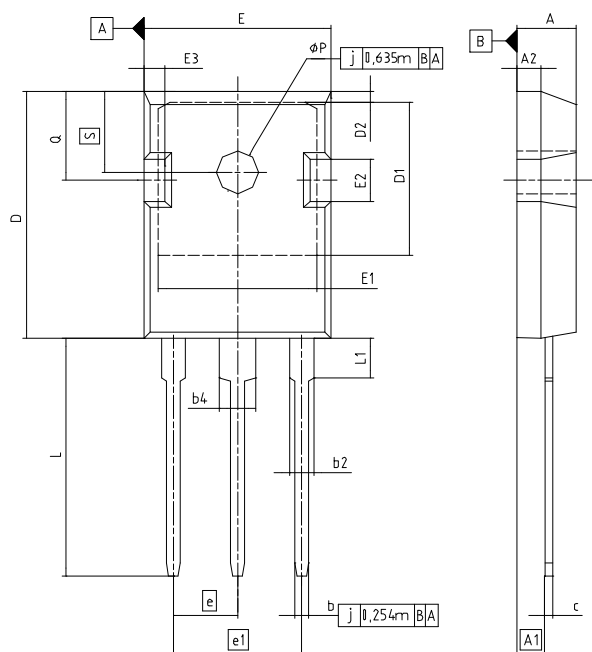


Figure 26. Typical diode forward voltage as a function of junction temperature



PG- TO247-3-21 / -41

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.16	0.193	0.203
A1	2.27	2.53	0.089	0.099
A2	1.85	2.11	0.073	0.083
b	1.07	1.33	0.042	0.052
b2	1.90	2.39	0.075	0.094
b4	2.87	3.45	0.113	0.136
c	0.55	0.75	0.022	0.030
D	20.82	21.10	0.820	0.831
D1	16.25	17.83	0.640	0.702
D2	1.05	1.35	0.041	0.053
E	15.70	16.03	0.618	0.631
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.68	2.60	0.066	0.102
e	5.44		0.214	
e1	10.90		0.429	
N	3		3	
L	19.80	20.31	0.780	0.799
L1	4.17	4.47	0.164	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

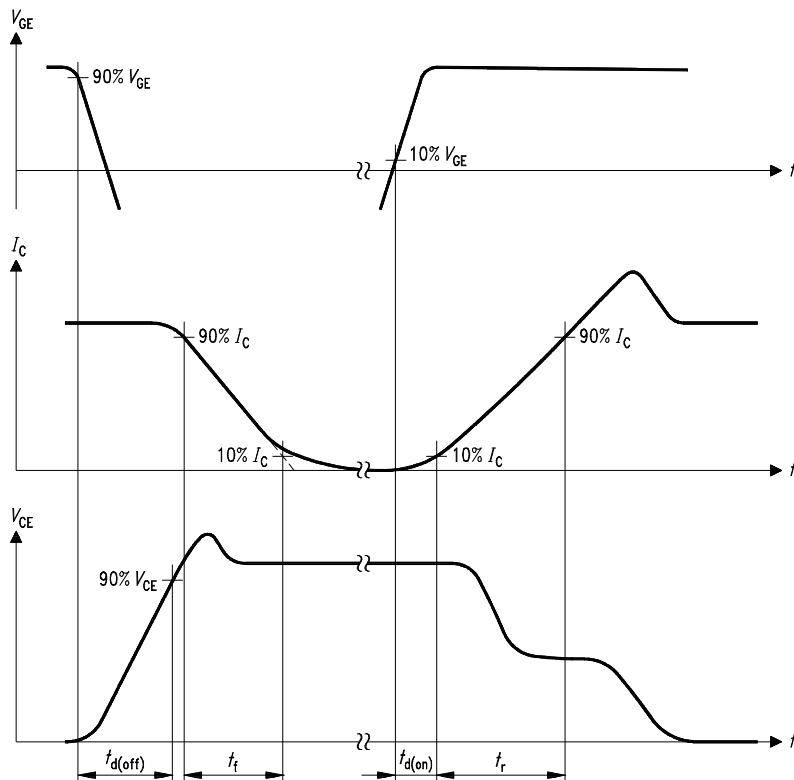


Figure A. Definition of switching times

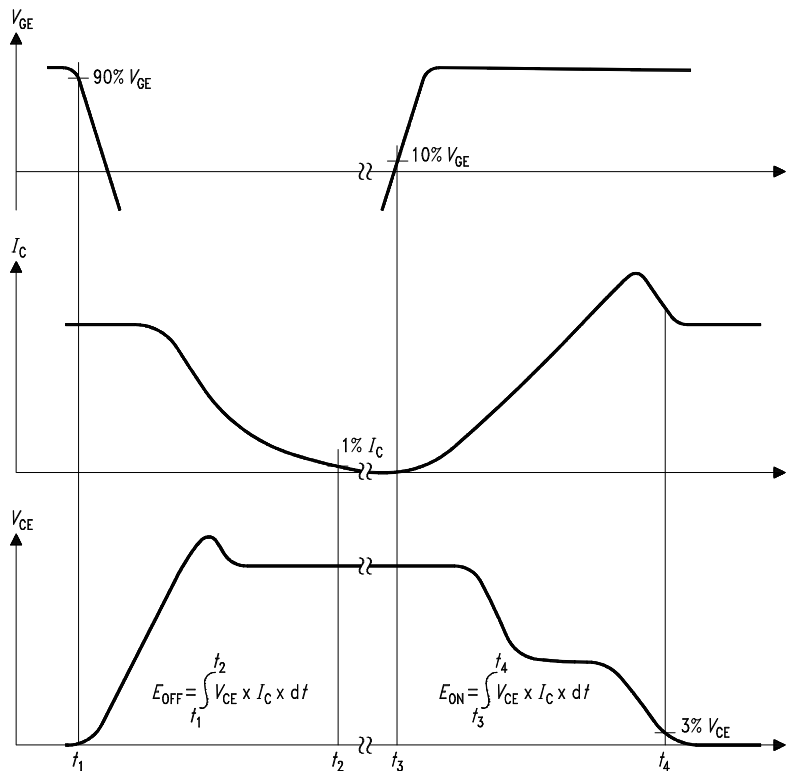


Figure B. Definition of switching losses

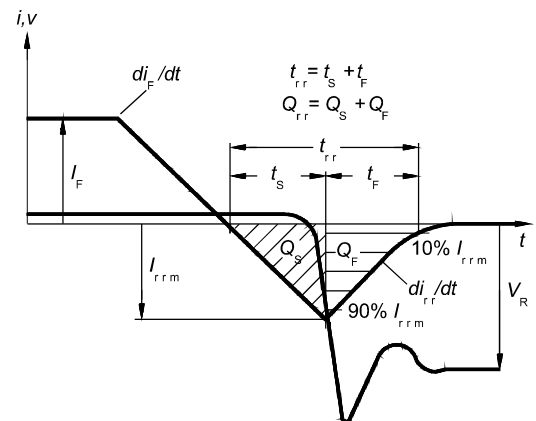


Figure C. Definition of diodes switching characteristics

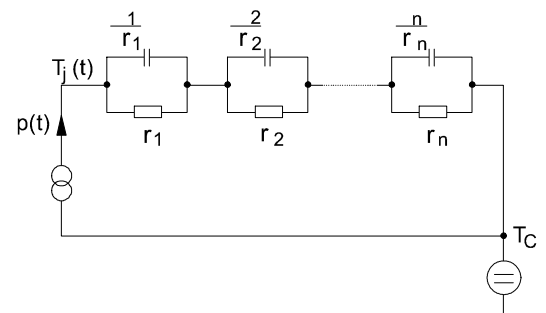


Figure D. Thermal equivalent circuit

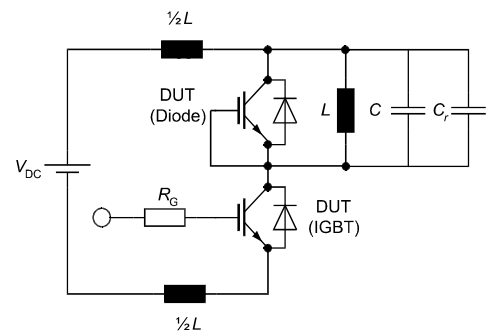


Figure E. Dynamic test circuit

Leakage inductance $L = 180\text{nH}$,
Stray capacitor $C_g = 40\text{pF}$,
Relief capacitor $C_r = 1\text{nF}$
(only for ZVT switching)

Edition 2006-01

Published by

Infineon Technologies AG

81726 München, Germany

© Infineon Technologies AG 8/17/06.

All Rights Reserved.

Attention please!

The information given in this data sheet shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.